PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	AMS/22/13129
1.3 Title of PCN	BOM Changes (LF plating and DA) on VIPER products (TFME subcon as assy plant).
1.4 Product Category	Pls Refer to the enclosed Products List.
1.5 Issue date	2022-01-10

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO
2.1.2 Marketing Manager	Vittorio GIAMMELLO
2.1.3 Quality Manager	Alessandro PLATINI

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), Die Attach material	TFME subcon as assy plant

4. Description of change

	Old	**New**
4.1 Description	Leadframe Die Attach Pad: Ag Plated Die Attach Material: Ablestik 8390S	Leadframe Die Attach Pad: Ag Plated with Cu Ring Die Attach Material: Ablebond 8200T
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on form, fit, function, reliability, or processability.	

5. Reason / motivation for change

5.1 Motivation	Standardization of materials within the product family.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	New FGs

7. Timing / schedule

7.1 Date of qualification results	2021-03-05
7.2 Intended start of delivery	2022-07-08
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13129 RR_DIP7 and DIP8.zip		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2022-01-10

9. Attachments (additional documentations)
13129 Public product.pdf 13129 RR_DIP7 and DIP8.zip

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	VIPER17LN	

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